Build Up HDI (Standard)

HDI08_1+6b+1_1,25_35_engl

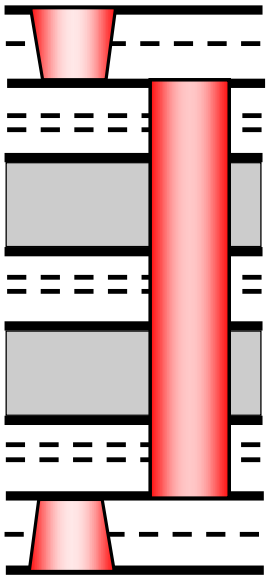
8 - Layers

Core: 0,25 mm Cu 35/35 µm

WE-Articel No.:

1 + 6B + 1

Customer:

layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE					[µm]	[µm]
	TOP/VS		Foil	12 µm	1)	12	
					1 x 1080	58	
	2		Foil	9 µm		30	
					2 x 1080	133	
	3			35 µm		33	
			0,250 mm			250	
	4			35 µm		33	
					2 x 1080	124	
	5			35 µm		33	
			0,250 mm			250	
	6			35 µm		33	
					2 x 1080	133	
	7		Foil	9 µm		30	
					1 x 1080	58	
	BOT/RS		Foil	12 µm	1)	12	

1) copper thickness outer layers: appr. 55 µm

total material thickness: 1222

Note: Lamination thickness for Prepregs depending on layout characteristics.

final lamination thickness:	**1,22**	+/-	0,10	mm			Date:	Engineer:
thickness with electro plated Cu:	1,31	+/-	0,13	mm				
total thickness with soldermask	1,37	+/-	0,15	mm				
customer requirement		+/-		mm	point:			

prepared: on	by	checked: on	by	approved: on	by	revision	page:
25.04.2006	**S. Keller**	04.05.2006	M.Kress	25.04.2006	R. Schönholz	00	15+